SV SensTech

华景传感科技

Data Sheet

Version 1.0/Jul 2022

ML-2659-4030-DT1H1

拥有核心芯片技术的MEMS传感技术公司

A MEMS Sensor Company with Advanced Core Chip Technology

上海
芯片研发：上海张江

无锡
研发测试中心：无锡高新区

北京
华北销售中心：北京海淀

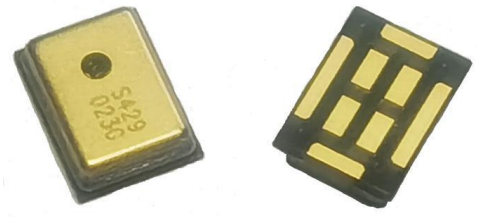
德国
芯片研发：斯图加特

苏州
封测生产：苏州高新区

深圳
华南销售中心：深圳南山

Product Specification

ML-2659-4030-DT1H1
Top-port digital silicon microphone



Description

ML-2659-4030-DT1H1 is a miniature digital top-port silicon microphone that receives the sound signal from the top hole on PCB. By using our own innovative and unique MEMS microphone chip design, SV Senstech provides a series of packaged MEMS silicon microphones with compact size to achieve excellent performance such as high SNR, high AOP, excellent reliability and broadband frequency response. This series of MEMS microphones find wide applications in laptops, automotives, cell phones, TWS, wearable devices and other portable electronic devices.

Features

- Compact size of 4.0×3.0×1.0 mm^3
- Sensitivity of -26dBFS (±1dBFS)
- High signal-to-noise ratio of 59 dB
- Extreme low THD of 0.1% at 94 dB SPL
- PDM Output
- High immune to RF/EM interference
- High mechanical strength
- High temperature resistance
- Excellent reliability

Applications

Laptops, automotives, smartphones, Bluetooth headsets/headphones, TWS, wearable electronics, IoT related devices, etc.

Absolute maximum ratings

Parameter	Absolute Maximum Rating	Units
Vdd, DATA to Ground	-0.3, +5.0	V
CLOCK to Ground	-0.3, +5.0	V
SELECT to Ground	-0.3, +5.0	V
Input Current	±5	mA
Short Circuit to/from DATA	Indefinite to Ground or Vdd	sec
Temperature	-40 to +100	°C

Notes:

1) Stresses exceeding these "Absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only.
2) Functional operation at these or any other conditions beyond those indicated under "Acoustic and electrical specifications" is not implied.
3) Exposure beyond those indicated under "Acoustic and electrical specifications" for extended periods may affect device reliability.

Acoustic and electrical specifications

General Microphone Specifications

Test conditions: 23°C±2°C, 55%±5% R.H., VDD=1.8V, Fclock=2.4 MHz, SELECT grounded, no load, 100nF capacitor between VDD and GND,unless otherwise indicated

Parameter		Symbol	Condition	Min.	Typ.	Max	Unit
Supply Voltage		Vdd		1.6		3.6	V
Sleep Current		Isleep	Fclock≤1kHz		32	42	μA
Clock Frequency Range	Sleep Mode	Fclock		0		50	kHz
	Low Power Mode	Fclock		250	768	900	kHz
	Normal Mode	Fclock		1.024	2.4	4.8	MHz
Clock Duty Cycle				40	50	60	%
Directivity				Omnidirectional			
Data Format				1/2 Cycle 1-bit PDM			
Output Load		Cload				140	pF
Fall Asleep Time		Tslp	Fclock≤50kHz		5		μs
Wake-up Time		Twk	Fclock>150kHz		30		μs
Power-up Time		Tpu			35		μs
Mode Change Time		Tmc				10	μs
Dimension				4.0×3.0×1.0			mm^3
Directivity				Omnidirectional			
Frequency Response		F		100~10k			Hz

Normal Mode

Test conditions: 23°C±2°C, 55%±5% R.H., VDD=1.8V, Fclock=2.4 MHz, SELECT grounded, no load, 100nF capacitor between VDD and GND,unless otherwise indicated

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Sensitivity	Sens	94dB SPL @1kHZ	-27	-26	-25	dBFS
Signal to noise ratio	SNR	94dB SPL @1kHz		59		dB(A)
Current Consumption	Idd	Fclock=2.4MHz		920		μA

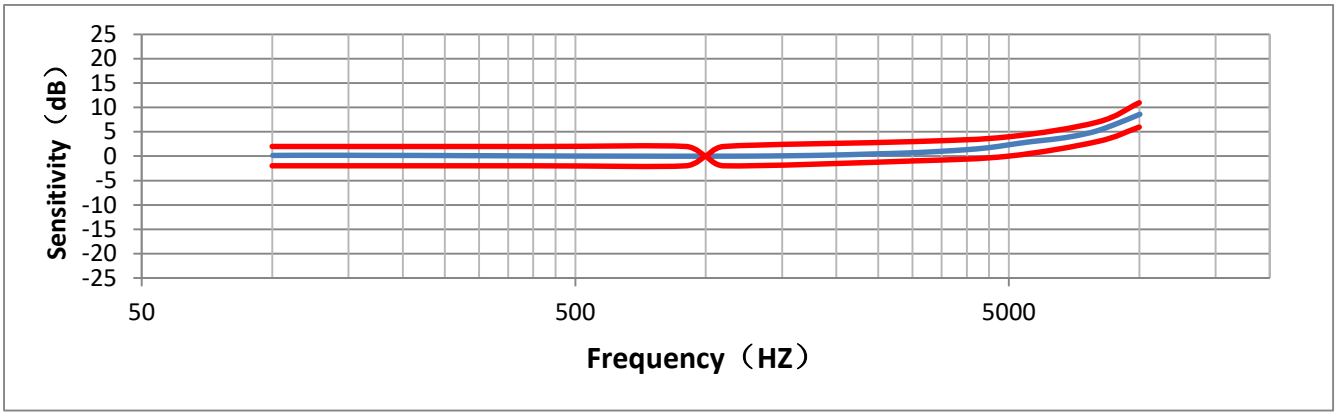
Total Harmonic Distortion	THD	94 dB SPL @ 1kHz		0.1		%
Acoustic Overload Point	AOP	10% THD @ 1kHz		115		dBSPL
Power Supply Rejection	PSR	100mVpp square wave @ 217 Hz, A-weighted		-87		dBFS(A)
Power Supply Rejection Ratio	PSRR	200mVpp sine wave @1kHz		54		dBV/FS

Low-Power Mode

Test conditions: 23°C±2°C, 55%±5% R.H., VDD=1.8V, Fclock=768kHz, SELECT grounded, no load, 100nF capacitor between VDD and GND,unless otherwise indicated

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Sensitivity	Sens	94dB SPL @1kHz	-27	-26	-25	dBFS
Signal to Noise Ratio	SNR	94dB SPL @1kHz,A-weighted (BW=8kHz)		59		dB(A)
Current Consumption	Idd			380		μA
Total Harmonic Distortion	THD	94 dB SPL @1kHz		0.1		%
Acoustic Overload Point	AOP	10% THD @1kHz		115		dBSPL
Power Supply Rejection	PSR	100mVpp square wave @ 217 Hz, A-weighted		-87		dBFS(A)
Power Supply Rejection Ratio	PSRR	200mVpp sine wave @1kHz		54		dBV/FS

Frequency response

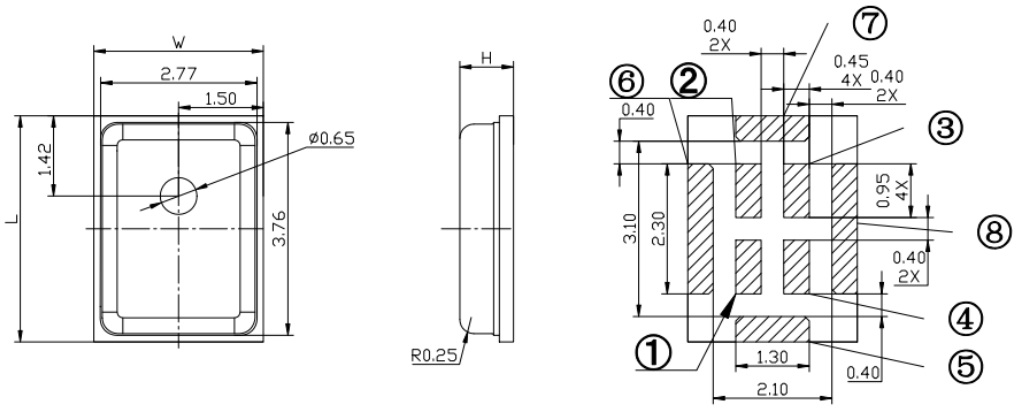


	100	400	900	1000	1100	3000	5000	8000	10000
USL	2	2	2	0	2	3	4	7	11
LSL	-2	-2	-2	0	-2	-1	0	3	6

Figure 1. Typical free field frequency response (normalized to 1 kHz)

Mechanical specifications

Top view Side view Bottom view

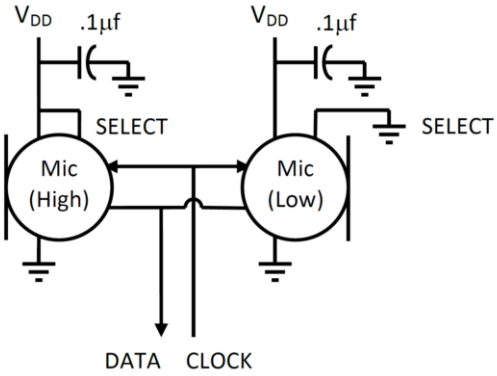


Dimension		
Item	Dimension	Tolerance
Length(L)	4.0 mm	±0.1 mm
Width(W)	3.0 mm	±0.1 mm
Height(H)	1.0 mm	±0.1 mm
AP	0.65mm	±0.05 mm

Pin #	Pin Name
①	VDD
②	SELECT
③	CLOCK
④	DATA
⑤~⑧	GND

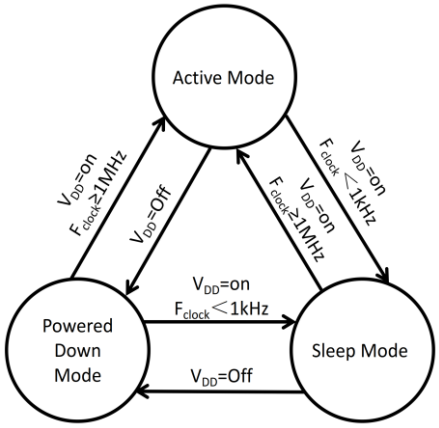
Figure 2. Detailed mechanical drawings

- **Interface circuit**



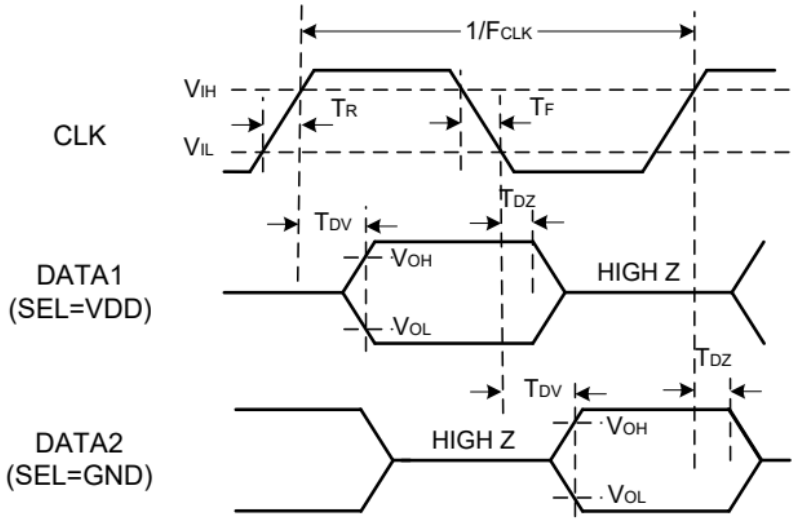
Microphone	SELECT	Asserts DATA On	Latch DATA On
Mic (High)	V_{DD}	Rising Clock Edge	Falling Clock Edge
Mic (Low)	GND	Falling Clock Edge	Rising Clock Edge

- **Device state diagram**



- **Time diagram**

Parameter	Symbol	Min	Typ	Max	Conditions
Time required for data valid on the rising edge clock	t_{dvr}	24 ns		48 ns	R_L=1 MΩ, C_L=12 pF
Time required for data valid on the falling edge clock	t_{dvf}	24 ns		48 ns	R_L=1 MΩ, C_L=12 pF
Time required for data to be Z	t_{dz}	0 ns		20 ns	R_L=1 MΩ, C_L=12 pF



- **Example land pattern**

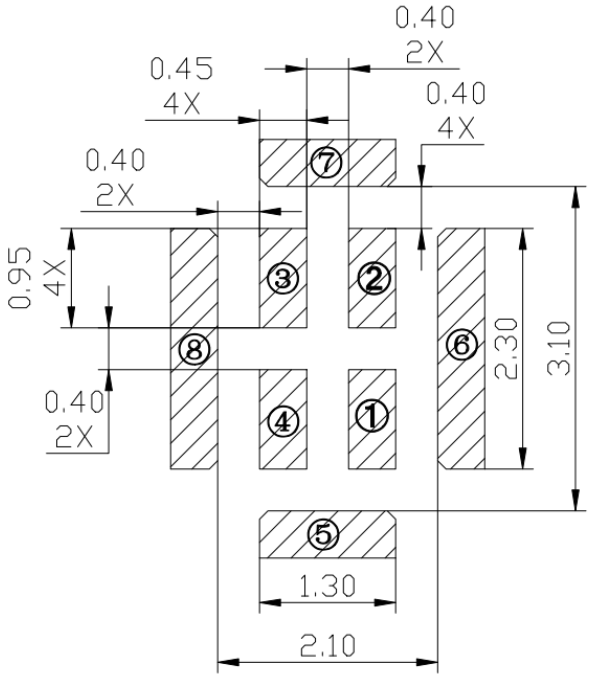
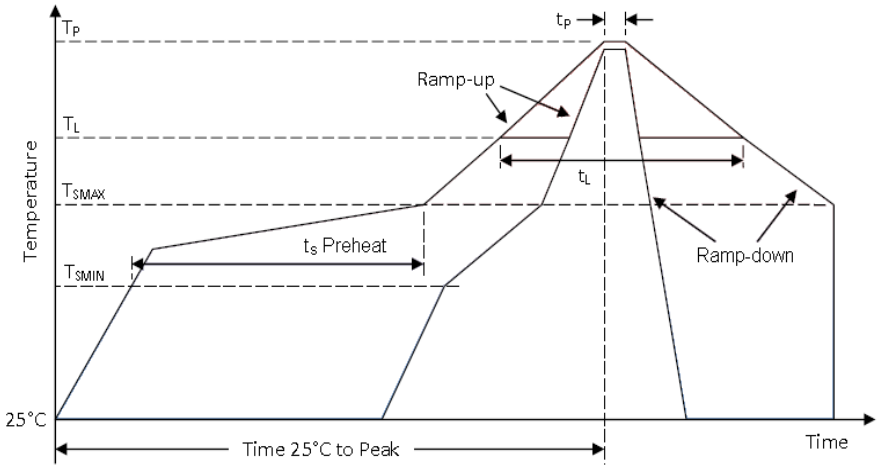


Figure 3. Recommended landing pattern on customers' PCB

Recommended reflow profile



Description		Parameter（lead-free）
Average temperature change rate (T_{SMAX} to T_P)		3ºC/second max.
Preheat	Minimum temperature (T_{SMIN}) Maximum temperature (T_{SMAX}) Time (T_{SMIN} to T_{SMAX}) (t_S)	150ºC 200ºC 60-180 seconds
Reflow	Temperature (T_L) Time (t_L)	217ºC 60-150 seconds
Peak temperature	Temperature (T_P) Time（t_P）	260ºC 20-40 seconds
Cooling rate(T_P to T_{SMAX})		6ºC/second max
Time required from 25ºC to peak temperature		8 minutes max

Figure 4. Recommended leadless solder reflow temperature profile

Notes:

5) The air blow speed during reflow process should be low to avoid impurity entering the acoustic hole during reflow process.

6) Do not wash or clean the product to avoid impurity entering the product.

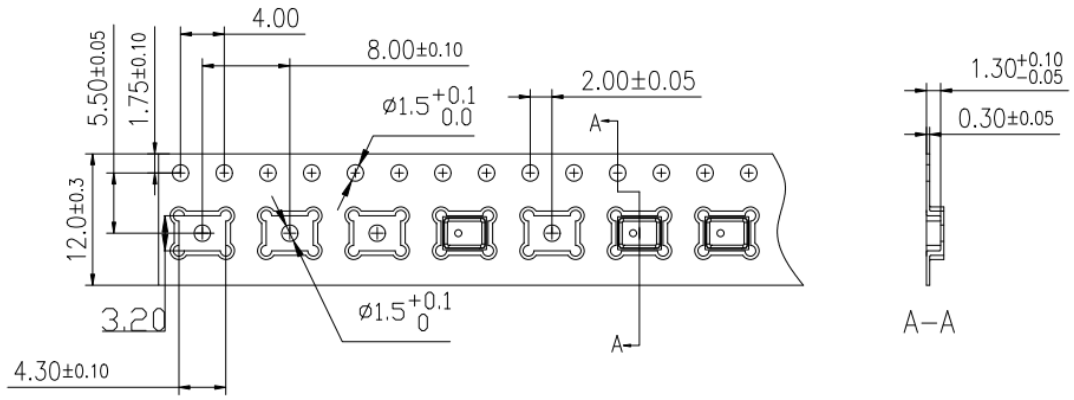
7) Do not carry out the reflow process more than 5 times. If the melting point of solders is lower, the peak temperature should be accordingly reduced.

Reliability specifications

Test Item	Description
Temperature/Humidity Bias	1,000 hours at +85℃/85% R.H. under bias (JESD22-A101A-B)
Thermal shock	100 cycles air-to-air thermal shock from -40℃ to +125℃ with 15minute soaks.(IEC 68-2-4)
High Temperature Storage	1,000 hours at +105℃ environment(IEC 68-2-2)
Low Temperature Storage	1,000 hours at -40℃ environment(IEC 68-2-1)
High Temperature Bias	1,000 hours at +105℃ under bias(IEC 68-2-2)
Low Temperature Bias	1,000 hours at -40℃ under bias(IEC 68-2-1)
Drop test	Using 150g fixture, 3 drops along each of 6 axes from 1.5m height onto slippery marble floor(IEC 68-2-27)
ESD-HBM	3 discharges of ±2 kV direct contact to I/O pins. (MIL 883E, Method 3015.7)
ESD-LID/GND	3 discharges of ±8 kV direct contact to lid while unit is grounded. (IEC 61000-4-2)
ESD-MM	3 discharges of ±200 V direct contact to I/O pins. (ESD STM5.2)
Vibration test	4 cycles of 20 to 2,000 Hz sinusoidal sweep with 20 G peak acceleration lasting 12 minutes in X, Y, and Z directions (Mil-Std-883E, Method 2007.2 A)
Reflow test	5 reflow cycles with peak temperature of +260℃
Mechanical Shock	3 pulses of 10,000 G in the X, Y, and Z direction (IEC 68-2-27, Test Ea)

Notes: After reliability tests are performed, the sensitivity of the microphones shall not deviate more than 3 dB from its initial value. After 3 reflow cycles, the sensitivity of the microphone shall not deviate more than 3dB from its initial value.

Packaging and marking detail



Model Number	Reel Diameter	Quantity Per Reel	Quantity Per Carton
ML-2659-4030-DT1H1	13”	5,000	5,000 * 10 = 50,000Pcs

Notes:

1) Dice are packaged in black carrier band which uses anti-electrostatic material. Each volume of packaged products is 5000 pcs.
2) The space between two dice is 8mm packaged in the carrier band with 12-mm width rolled in the reel of 13-inch diameter.
3) The package requirements mentioned below is the company’s standard delivery specifications. If you need special packages, please contact our sales staff.
4) All dimensions are in millimeters (mm) with tolerance of ± 0.3mm.

Materials statement

- Meets the requirements of the European RoHS directive 2011/65/EC as amended.
- Meets the requirements of the industry standard IEC 61249-2-21:2003 for halogenated substances and SV SensTech Green Materials Standards Policy section on Halogen-Free.

Remarks

- MSL (moisture sensitivity level) Class 1.
- Maximum of 3 reflow cycles is recommended.
- In order to minimize device damage:
  - Do not board wash or clean after the reflow process.
  - Do not brush board with or without solvents after the reflow process.
  - Do not directly expose to ultrasonic processing, welding, or cleaning.
  - Do not insert any object in the port hole of device at any time.
  - Do not apply over 30 psi of air pressure into the port hole.
  - Do not pull a vacuum over the port hole of microphone.
  - Do not apply a vacuum when repacking into sealed bags at a rate faster than 0.5 atm/sec.

Version updates

Version	Updated Content	Updated Date
1.0	Initial release	2022-7-28

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